



## **LOGITECH WSB2 WAFER SUBSTRATE BONDING UNIT**

### **BONDING SPECIFICATIONS**

Bond Equipment : Logitech WSB2 Wafer to Substrate Bonder

Bond Temp : 85°C

Wax Soak Time : 5 mins

Bond Time : 15 mins

Bond Wax : Quartz

Vacuum Level : 1.5 to 3.5 E-1mbar

Applied Pressure : 15 psi